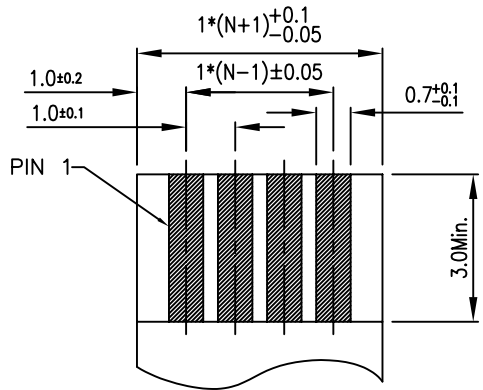
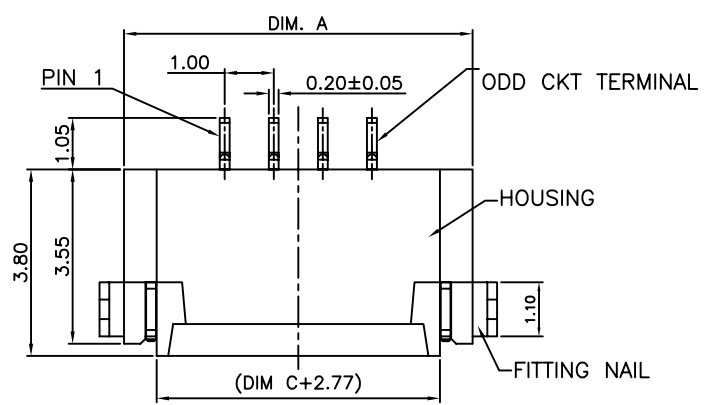


RECOMMENDED PCB LAYOUT



APPLICABLE FPC/FFC THICKNESS 0.3±0.03

- NOTES:
- MATERIAL:
 - HOUSING: THERMOPLASTIC, HIGH TEMP.,UL94V-0;
 - CONTACT: COPPER ALLOY
 - FITTING NAIL: COPPER ALLOY
 - FINISH:
 - CONTACT:
 - 50u" MIN. NICKEL UNDERPLATING OVERALL.
 - 1: GOLD FLASH OVER ALL
 - N: 120u" MIN MATT TIN OVER ALL.
 - FITTING NAIL:
 - 50u" MIN. NICKEL UNDERPLATING OVERALL.
 - 1: GOLD FLASH OVER ALL
 - N: 120u" MIN MATT TIN OVER ALL.
 - REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
 - SPEC. PLS. REFER TO PS-50620-XXXX-XXX
 - PACKAGE PLS. REFER TO 91523-XXXX-TRP.



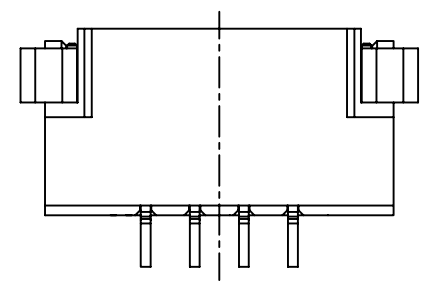
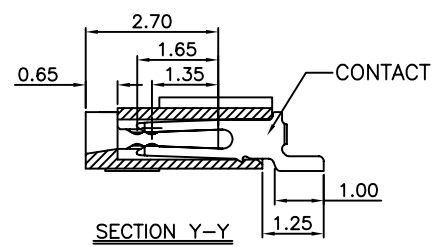
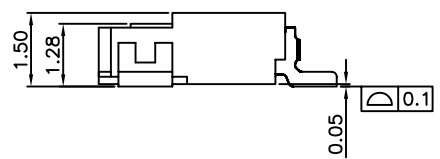
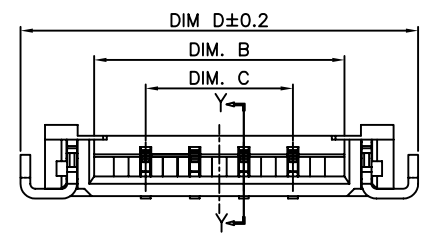
50678-XXX X X-XXX

NO OF CKT: XXX
 PACKING: 0:TAPE & REEL, 1:TUBE

PLATING:
 N:MATT TIN(LEAD FREE)
 1:GOLD FLASH OVER ALL(LEAD FREE)

XXX	HOUSING MATERIAL&COLOR	Halogen Free
001	HF&Black	HF
002	HF&Natural	HF

CKT	DIM. A	DIM. B	DIM. C	DIM. D
4	7.1	5.1	3.0	8.1
5	8.1	6.1	4.0	9.1
6	9.1	7.1	5.0	10.1
7	10.1	8.1	6.0	11.1
8	11.1	9.1	7.0	12.1
9	12.1	10.1	8.0	13.1
10	13.1	11.1	9.0	14.1
11	14.1	12.1	10.0	15.1
12	15.1	13.1	11.0	16.1
13	16.1	14.1	12.0	17.1
14	17.1	15.1	13.0	18.1
15	18.1	16.1	14.0	19.1
16	19.1	17.1	15.0	20.1
17	20.1	18.1	16.0	21.1
18	21.1	19.1	17.0	22.1
19	22.1	20.1	18.0	23.1
20	23.1	21.1	19.0	24.1
21	24.1	22.1	20.0	25.1
22	25.1	23.1	21.0	26.1
23	26.1	24.1	22.0	27.1
24	27.1	25.1	23.0	28.1
25	28.1	26.1	24.0	29.1
26	29.1	27.1	25.0	30.1
27	30.1	28.1	26.0	31.1
28	31.1	29.1	27.0	32.1
29	32.1	30.1	28.0	33.1
30	33.1	31.1	29.0	34.1



一般公差
 TOLERANCES
 X ±0.5 XX ±0.15
 Y ±0.25 XXX ±0.1
 ANGLES ±2°

檢驗尺寸標示
 SYMBOLS ⊕ ⊗ INDICATE CLASSIFICATION DIMENSION
 ⊕ MARK IS CRITICAL DIM.
 ⊗ MARK IS MAJOR DIM.

表面處理 (FINISH)

宏致電子股份有限公司
 Aces Electronic Co.,Ltd.

品名 (TITLE): 1.0mm Pitch NON-ZIF FPC Conn.
 SMT R/A D/C Type

製圖 (DR): huamin
 '09/06/04
 審核 (CHKD): WGCH
 核准 (APPD): JASON

圖號 (DWG.NO): 50678-XXXX-XXX

比例 (SCALE): 10:1
 單位 (UNITS): mm

張數 (SHEET): 1 OF 1
 版數 (REV): A4 C